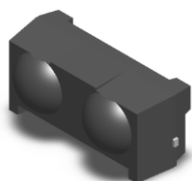


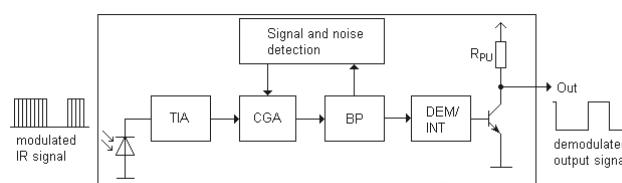
Infrared Receiver Module IRM-V8XXM3/TR1 Series



Pin Configuration

1. GND
2. VCC
3. OUT
4. GND

Block Diagram



Features

- Available for various carrier frequencies
- min burst length: 12 cycles
- min gap length: 16 cycles
- Low operating voltage and low power consumption
- High immunity against ambient light
- High immunity against TFT backlight
- Long reception range
- High sensitivity
- Pb free and RoHS compliant
- Compliance with EU REACH
- Compliance Halogen Free (Br < 900 ppm, Cl < 900 ppm, Br+Cl < 1500 ppm)

Description

The device is miniature SMD type infrared receiver that has been developed and designed by utilizing the latest IC technology.

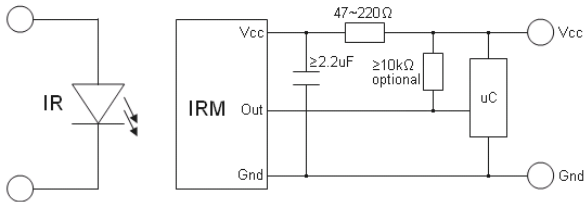
The PIN diode and preamplifier are assembled onto a lead frame and molded into a black epoxy package which operates as an IR filter.

The demodulated output signal can directly be decoded by a microprocessor.

Applications

- AV equipment such as TV, VCR, DVD, CD, MD, etc.
- CATV set top boxes
- Multi-media Equipment
- Other devices using IR remote control

Application Circuit



Parts Number Table

Model No.	Carrier Frequency
IRM-V836M3/TR1	36 kHz
IRM-V838M3/TR1	38 kHz
IRM-V856M3/TR1	56 kHz

Absolute Maximum Ratings (Ta=25°C) *1

Parameter	Symbol	Rating	Unit
Supply Voltage	Vcc	6	V
Operating Temperature	Topr	-20 ~ +85	°C
Storage Temperature	Tstg	-40 ~ +85	°C
Soldering Temperature *2	Tsol	260	°C

*1 Stresses in excess of the absolute maximum ratings can cause permanent damage to the device. Functional operation of the device is not implied at these or any other conditions in excess of those given in the operational sections of this document. Exposure to absolute maximum ratings for extended periods of the time can adversely affect reliability.

*2 Soldering time \leq 5 seconds

Electro-Optical Characteristics (Ta=25°C and Vcc=3.0V)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Current consumption	Icc	---	0.4	0.6	mA	No input signal
Supply voltage	Vcc	2.7	---	5.5	V	
Peak wavelength	λ_p	---	940	---	nm	
Reception range	L ₀	8	---	---	m	See chapter 'Test method' *3
	L ₄₅	5	---	---		
Half angle(horizontal)	ϕ_h	---	± 45	---	deg	
Half angle(vertical)	ϕ_v	---	± 45	---	deg	
High level pulse width	T _H	400	---	800	μ s	Test signal according to figure 1*4
Low level pulse width	T _L	400	---	800	μ s	
High level output voltage	V _{OH}	Vcc-0.4	---	---	V	I _{SOURCE} \leq 1 μ A
Low level output voltage	V _{OL}	---	0.2	0.5	V	I _{SINK} \leq 2mA

*3 The ray receiving surface at a vertex and relation to the ray axis in the range of $\theta=0^\circ$ and $\theta=45^\circ$.

*4 A range from 30cm to the arrival distance. Average value of 50 pulses.

Test method

The specified electro-optical characteristics are valid under the following conditions.

1. Measurement environment

A place without extreme light reflections.

2. External light

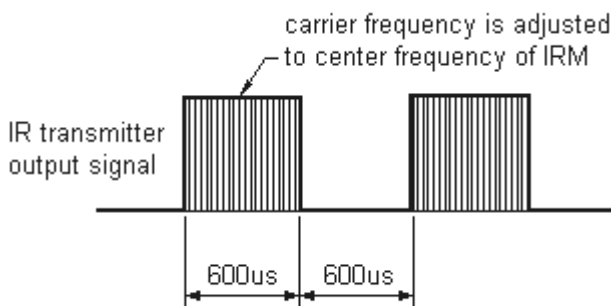
The environment contains an ordinary, white fluorescent lamp without high frequency modulation. The color temperature is 2856K and the illumination at the IR receiver is less than 10 Lux ($E_v \leq 10\text{Lux}$).

3. Standard transmitter

The test transmitter is calibrated by using the circuit shown in figure 2. The radiation intensity of the transmitter is adjusted until $V_o=400\text{mVp-p}$. Both the test transmitter and the photo diode have the peak wavelength of 940nm. The photo diode for calibration is PD438B ($\lambda_p=940\text{nm}$, $V_r=5\text{V}$).

4. The measurement system is shown in Fig.-3

Fig.-1 Transmitter Wave Form



D.U.T output Pulse

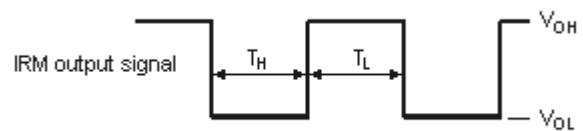


Fig.-2 Standard transmitter calibration

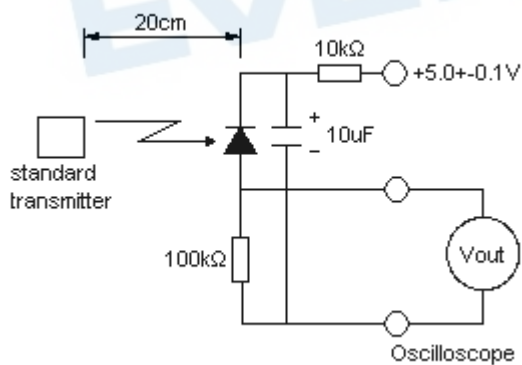
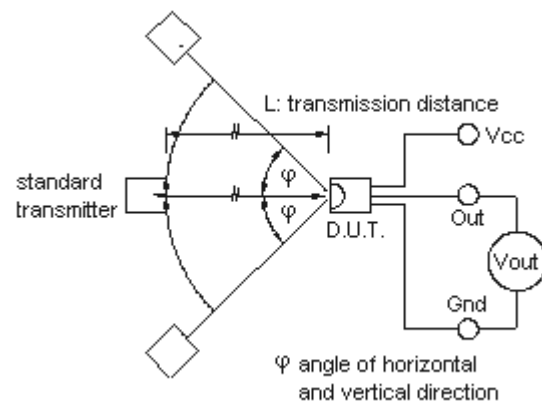


Fig.-3 Measuring System



Typical Electro-Optical Characteristics Curves

Fig.4 Relative Responsibility vs. Wavelength

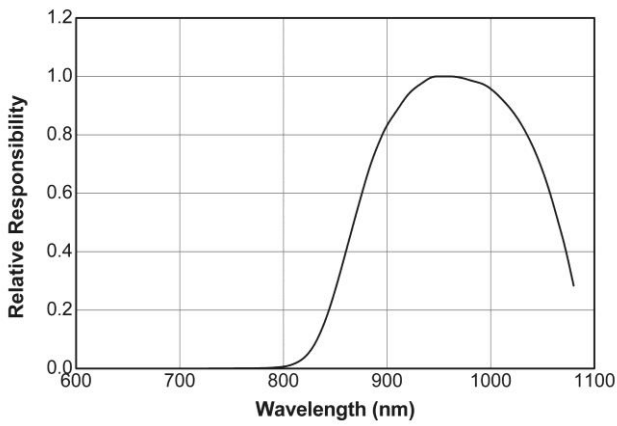


Fig.-5 Relative Sensitivity vs. Angle

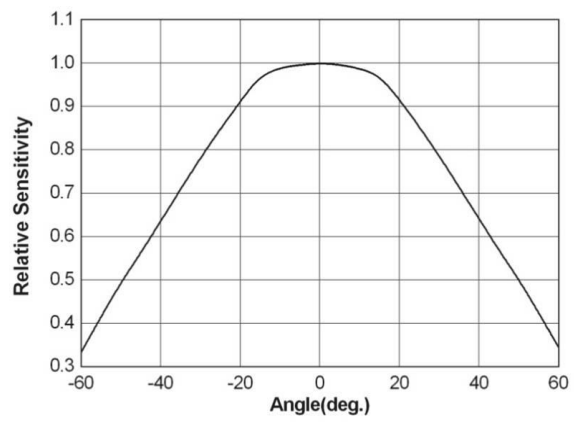


Fig.6 Variation Output Pulse Width vs. Distance

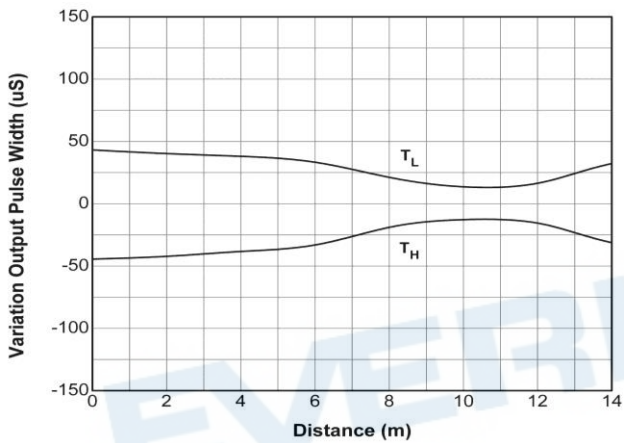


Fig.7 Relative Sensitivity vs. Supply Voltage

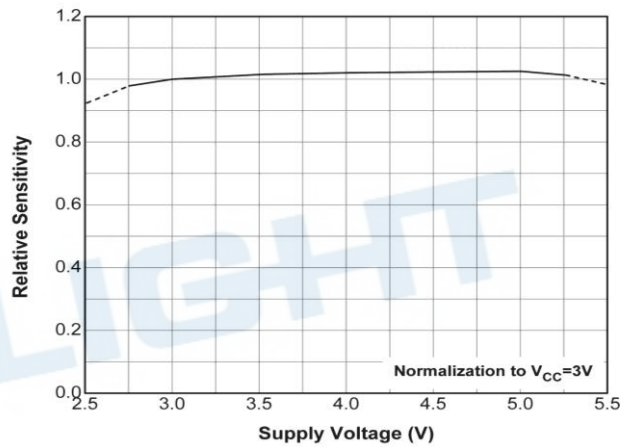
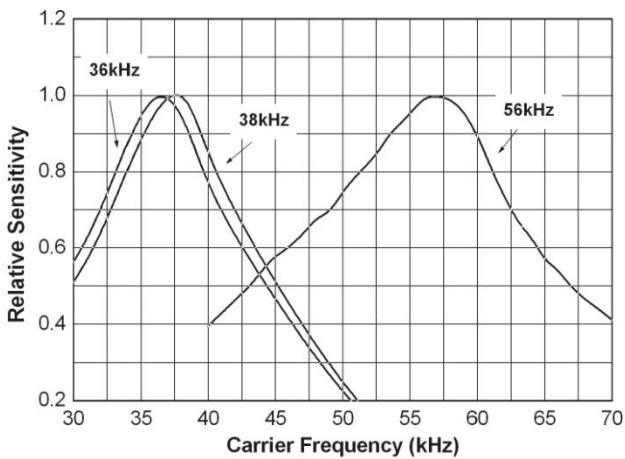
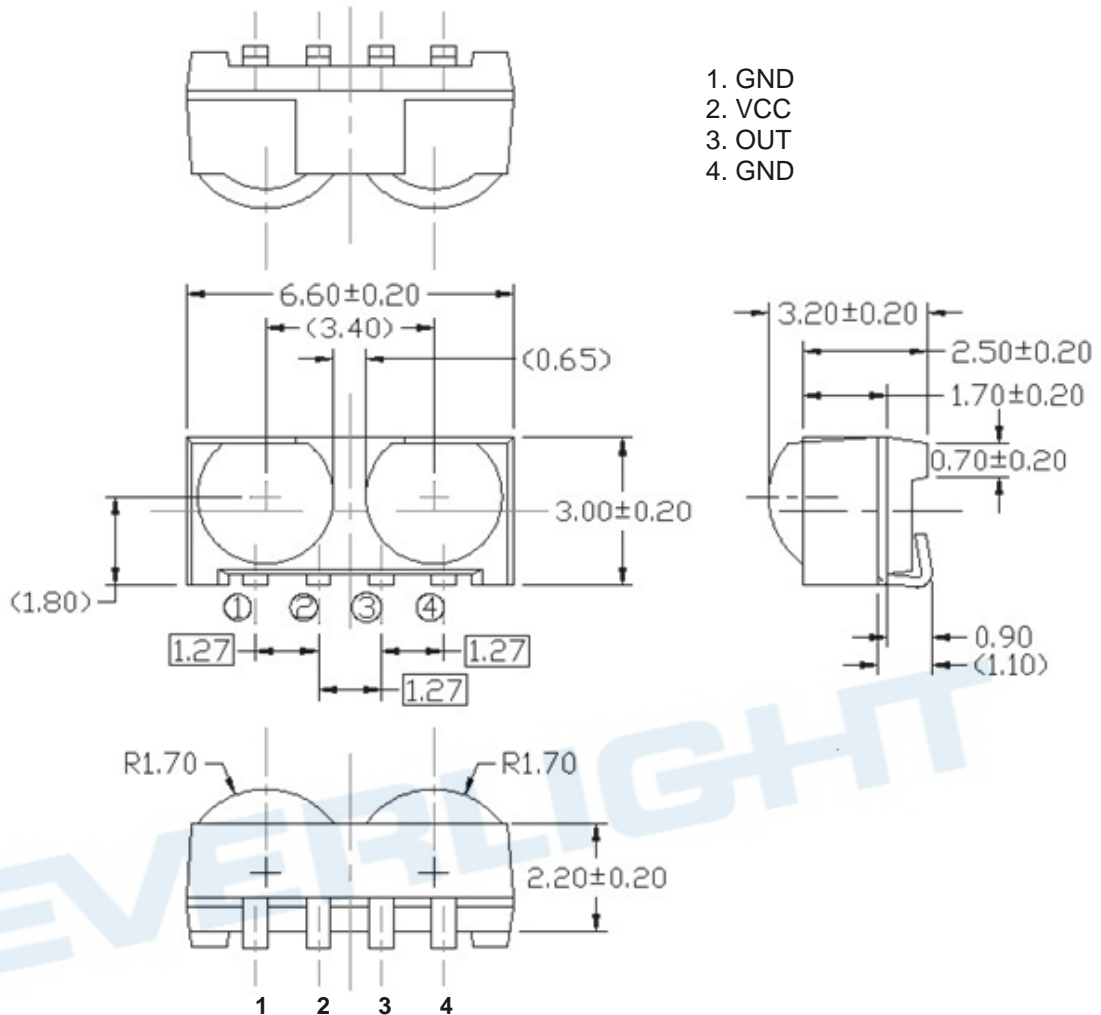


Fig.8 Relative Sensitivity vs. Carrier Frequency

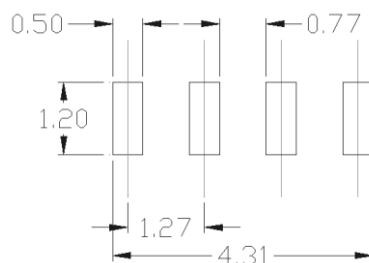


Package Dimension
(Dimensions in mm)



Note: Tolerances unless mentioned ± 0.5 mm. Unit: mm

Recommended pad layout for surface mount leadform



Notice: Suggested pad dimension is just for reference only.
Please modify the pad dimension based on individual need.

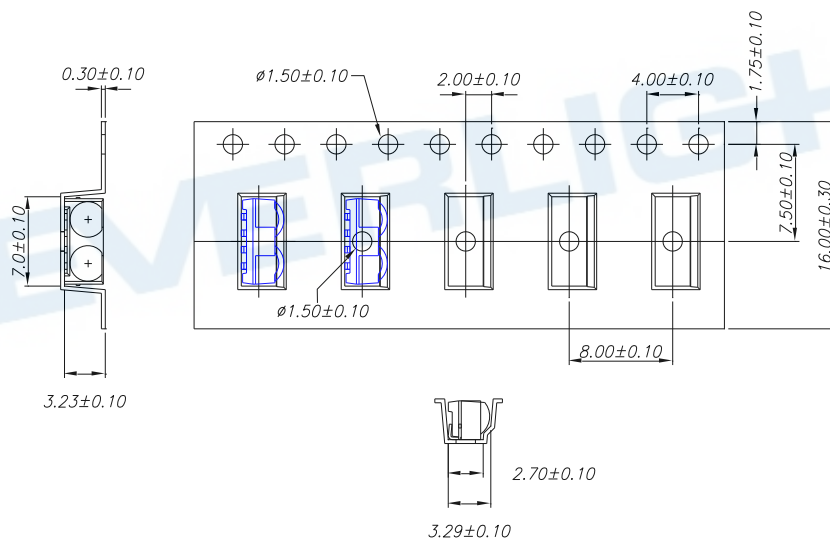
Code information

Protocol	Suitable	Protocol	Suitable
JVC	Yes	Sharp	Yes
Matsushita	Yes	Sony 12 bit ²⁾	Yes
Mitsubishi	No	Sony 15 bit	No
NEC	Yes	Sony 20 bit	No
RC5	Yes	Toshiba	Yes
RC6 ¹⁾	Yes	Continuous Code	No
RCA	No		

1) Best choice depends on RC6 mode. If data low time is below 22ms, M2 is the best choice, otherwise M3.

2) If only Sony 12 bit version is used, M3 is recommended otherwise M2 is the best choice.

Tape & Reel Packing Specifications (Dimensions in mm)



Packing Quantity

2000 pcs / Box
5 Boxes / Carton

Recommended method of storage

The following are general recommendations for moisture sensitive level (MSL) 4 storage and use:

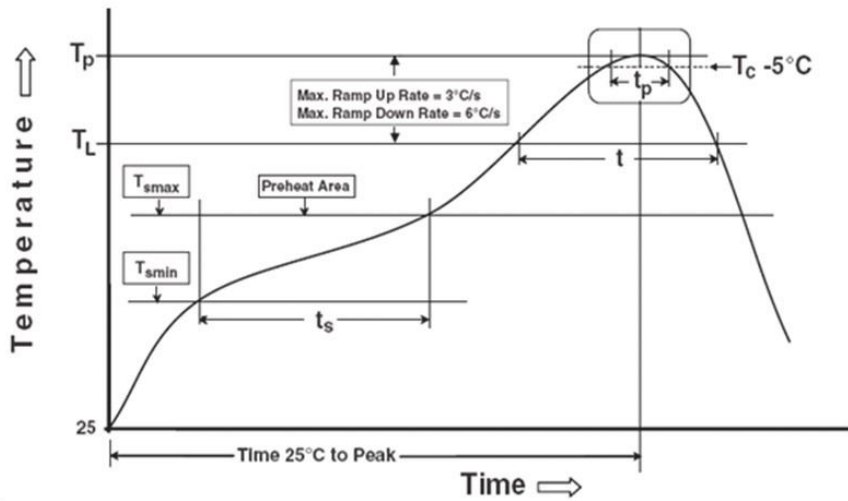
1. Do not open moisture proof bag before devices are ready to use.
2. Shelf life in sealed bag from the bag seal date: 12 months at 10°C~30°C and < 90% RH.
3. After opening the package, the devices must be stored at 10°C~30°C and ≤ 60%RH, and used within 72 hours (floor life).
4. If the moisture absorbent material (desiccant material) has faded or unopened bag has exceeded the shelf life or devices (out of bag) have exceeded the floor life, baking treatment is required.
5. If baking is required, refer to IPC/JEDEC J-STD-033 for bake procedure or recommend the following conditions: 96 hours at 60°C ± 5°C and < 5 % RH.

ESD Precaution

Proper storage and handing procedures should be followed to prevent ESD damage to the devices especially when they are removed from the Anti-static bag. Electro-Static Sensitive Devices warning labels are on the packing.

EVERLIGHT

Solder Reflow Temperature Profile



Note:

Reference: IPC/JEDEC J-STD-020D

Preheat

Temperature min (T _{smin})	150 °C
Temperature max (T _{smax})	200°C
Time (T _{smin} to T _{smax}) (t _s)	60-120 seconds
Average ramp-up rate (T _{smax} to T _p)	3 °C/second max

Other

Liquidus Temperature (T _L)	217 °C
Time above Liquidus Temperature (t _L)	60-100 sec
Peak Temperature (T _P)	260°C
Time within 5 °C of Actual Peak Temperature: T _P - 5°C	30 s
Ramp- Down Rate from Peak Temperature	6°C /second max.
Time 25°C to peak temperature	8 minutes max.
Reflow times	2 times

Note:

1. Reflow soldering should not be done more than two times.
2. When soldering, do not put stress on the IRM device during heating.
3. After soldering, do not warp the circuit board.

DISCLAIMER

1. EVERLIGHT reserves the right(s) on the adjustment of product material mix for the specification.
2. The product meets EVERLIGHT published specification for a period of twelve (12) months from date of shipment.
3. The graphs shown in this datasheet are representing typical data only and do not show guaranteed values.
4. When using this product, please observe the absolute maximum ratings and the instructions for using outlined in these specification sheets. EVERLIGHT assumes no responsibility for any damage resulting from the use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.
5. These specification sheets include materials protected under copyright of EVERLIGHT. Reproduction in any form is prohibited without obtaining EVERLIGHT's prior consent.
6. This product is not intended to be used for military, aircraft, automotive, medical, life sustaining or life saving applications or any other application which can result in human injury or death. Please contact authorized Everlight sales agent for special application request.

EVERLIGHT

单击下面可查看定价，库存，交付和生命周期等信息

[>>Everlight \(亿光\)](#)